

SID

Factory: Rot am See

Article:

ML8

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: Pinlamination

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	231		2
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3
		35	L2	
A-RS-FR4-ML-0.254mm-035+035-TG150-HF-...	50203054	255	4	A01
		35	L3	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	216	5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0	6	
		35	L4	
A-RS-FR4-ML-0.254mm-035+035-TG150-HF-...	50203054	255	7	A02
		35	L5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	216	8	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0	9	
		35	L6	
A-RS-FR4-ML-0.254mm-035+035-TG150-HF-...	50203054	255	10	A03
		35	L7	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	231	11	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0	12	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	13

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1905 µm

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